Abstract

The present invention is directed to a method and apparatus for etching the interior of a mold. In one implementation of the invention the interior of a mold is coated with an acid-resistant material. A photosensitive laminate is partially exposed to light, with only those areas that are to be etched being exposed. The laminate is subsequently developed to remove that portion of the laminate that has been exposed. This removed portion corresponds to the portion of the mold that is to be etched. After development the laminate is positioned in the interior of the mold over the acid-resistant coating, and then portions of the acid-resistant material are abrasively removed. The laminate is lightly wetted in some implementations in order to make it more flexible and stretchable, thereby allowing it to more readily conform to the interior surface of the mold. The intact portions of the photosensitive laminate (those portions that were not exposed to the light) provide protection to the acid-resist material, while the developed and removed portions of the photosensitive laminate provide little or no protection.